

## N-Channel Enhancement Mode Power MOSFET

### Description

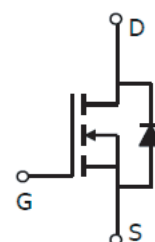
The RM5N150S8 uses advanced trench technology and design to provide excellent  $R_{DS(ON)}$  with low gate charge. It can be used in a wide variety of applications.

### General Features

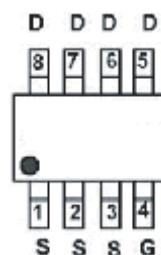
- $V_{DS} = 150V, I_D = 4.6A$
- $R_{DS(ON)} < 75m\Omega @ V_{GS}=10V$  (Typ:63m $\Omega$ )
- $R_{DS(ON)} < 88m\Omega @ V_{GS}=4.5V$  (Typ:70m $\Omega$ )
- Special process technology for high ESD capability
- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current

### Application

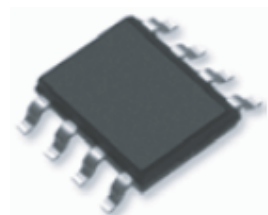
- DC/DC Primary Side Switch
- Telecom/Server
- Synchronous Rectification
- Halogen-free



Schematic diagram



Marking and pin assignment



SOP-8 top view

### Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
5N150	RM5N150S8	SOP-8	Ø330mm	12mm	4000 units

### Absolute Maximum Ratings ( $T_A=25^\circ C$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	$V_{DS}$	150	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current-Continuous	$I_D$	4.6	A
Drain Current-Continuous( $T_C=100^\circ C$ )	$I_D(100^\circ C)$	2.9	A
Pulsed Drain Current	$I_{DM}$	35	A
Maximum Power Dissipation	$P_D$	3.1	W
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 To 150	$^\circ C$

### Thermal Characteristic

Thermal Resistance, Junction-to-Ambient <sup>(Note 2)</sup>	$R_{\theta JA}$	40	$^\circ C/W$
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## Electrical Characteristics (T<sub>A</sub>=25°C unless otherwise noted)

### Static Characteristics

Parameter	Symbol	Conditions	Value			Unit
			min	typ	max	
Drain to Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	150	-	-	V
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250μA	1	2	3	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>GS</sub> =0V, V <sub>DS</sub> =150V, T <sub>J</sub> =25°C	-	-	1	μA
		V <sub>GS</sub> =0V, V <sub>DS</sub> =150V, T <sub>J</sub> =100°C	-	-	100	
Gate to Source Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	-	-	±100	nA
Drain to Source on Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =5A	-	63	75	mΩ
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =4A	-	70	88	
Transconductance	g <sub>fs</sub>	V <sub>DS</sub> =5V, I <sub>D</sub> =5A	-	18	-	S
Gate Resistance	R <sub>G</sub>	V <sub>GS</sub> =0V, V <sub>DS</sub> Open, f=1MHz	-	5.0	-	Ω

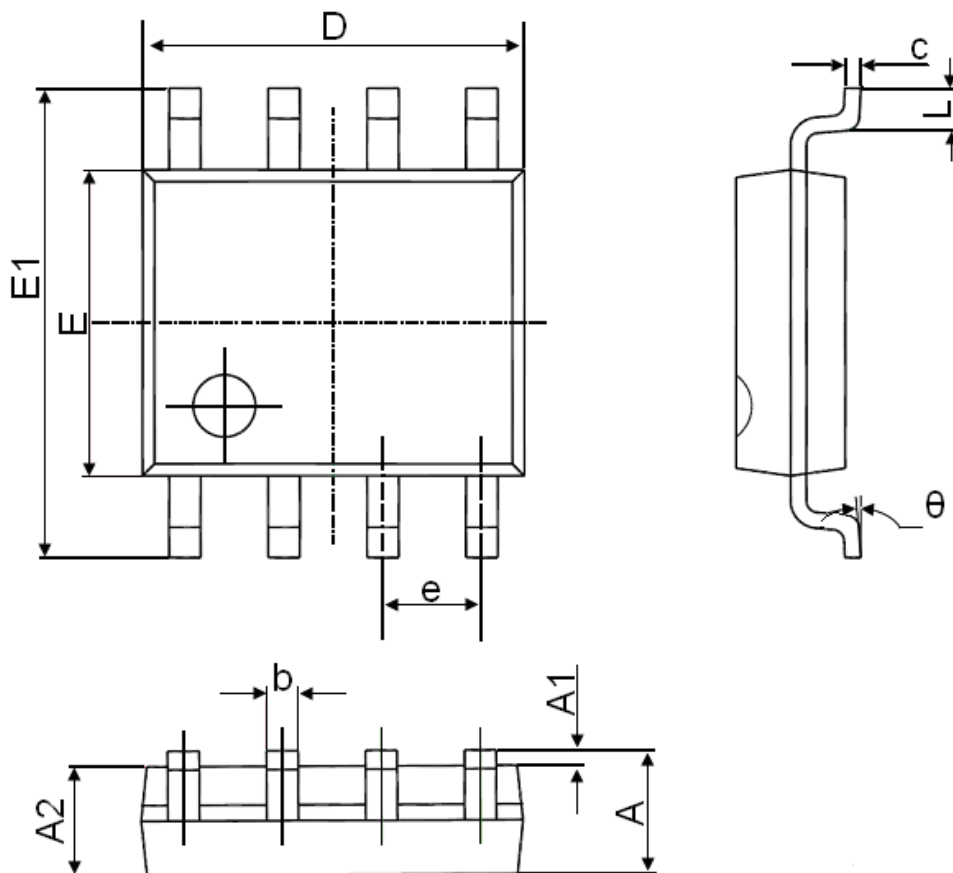
### Dynamic Characteristics

Input Capacitance	C <sub>iss</sub>	V <sub>GS</sub> =0V, V <sub>DS</sub> =75V, f=1MHz	-	625	-	pF
Output Capacitance	C <sub>oss</sub>		-	37	-	
Reverse Transfer Capacitance	C <sub>rss</sub>		-	13	-	
Total Gate Charge (10V)	Q <sub>g</sub> (10V)	V <sub>DD</sub> =75V, I <sub>D</sub> =5A, V <sub>GS</sub> =10V	-	11.6	-	nC
Total Gate Charge (4.5V)	Q <sub>g</sub> (4.5V)		-	6.5	-	
Gate to Source Charge	Q <sub>gs</sub>		-	1.2	-	
Gate to Drain (Miller) Charge	Q <sub>gd</sub>		-	4	-	
Turn on Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> =75V, I <sub>D</sub> =5A, V <sub>GS</sub> =10V, R <sub>G</sub> =10Ω,	-	10	-	ns
Rise time	t <sub>r</sub>		-	7	-	
Turn off Delay Time	t <sub>d(off)</sub>		-	14	-	
Fall Time	t <sub>f</sub>		-	3	-	

### Reverse Diode Characteristics

Diode Forward Voltage	V <sub>SD</sub>	V <sub>GS</sub> =0V, I <sub>F</sub> =5A	-	0.9	1.2	V
Reverse Recovery Time	t <sub>rr</sub>	V <sub>R</sub> =75V, I <sub>F</sub> =5A, dI <sub>F</sub> /dt=100A/μs	-	50	-	ns
Reverse Recovery Charge	Q <sub>rr</sub>		-	70	-	nC

## SOP-8 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270(BSC)		0.050(BSC)	
L	0.400	1.270	0.016	0.050
$\theta$	0°	8°	0°	8°

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